

**SPECIFICATION OF LED CHIP
C1450-35
[NIR]**

1) Commodity Type and Physical Characteristics.

- | | |
|----------------------|-------------------------------------------------------------------------------|
| 1. Material | InGaAsP/InP(DDH) |
| 2. Electrode | Top Side P (anode) side : Au Alloy
Bottom Side N (cathode) side : Au Alloy |
| 3. Electrode Pattern | Fig.1 |
| 4. Chip Size | Fig.2 |
| 5. Chip Thickness | Fig.2 |
| 6. Emission Area | Fig.2 |

2) Electro-Optical Characteristics

parameters	symbol	condition	min.	typ.	max.	unit
Forward Voltage	Vf	If=20mA		0.8	1.3	V
Reverse Current	Ir	Vr=3V			10	uA
Power Intensity	Po	If=20mA		0.4		mW
Peak Wavelength	λ P	If=20mA		1450		nm
Spectral Radiation Bandwidth	DI	If=20mA		100		nm
RiseTime	tr	If=20mA		10		ns
FallTime	tf	If=20mA		10		ns

‡ Die shall be mounted on TO=18 gold header without resin coated. (Ta=25°C)

[Unit: um]

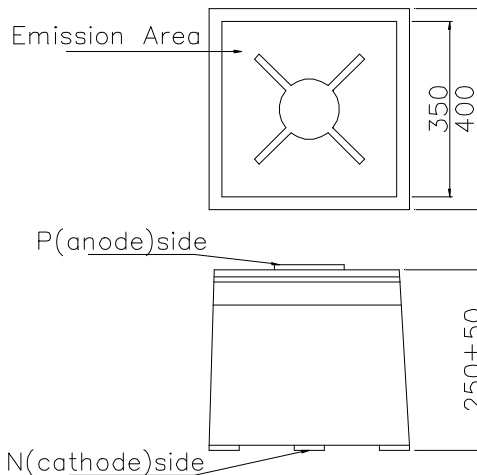
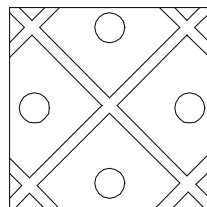
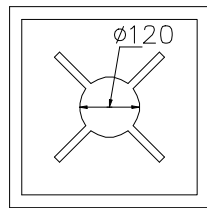


Fig.1 Electrode Pattern

Fig.2 Chip size and Emission Area